



Material Content Data Sheet



Sales Product Name		SPA11N80C3		Issued		21. September 2015			
MA#		MA001408794							
Package		PG-TO220-3-253		Weight*		2136.05 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	9.366	0.44	0.44	4385	4385	
leadframe	non noble metal	iron	7439-89-6	1.431	0.07		670		
	inorganic material	phosphorus	7723-14-0	0.429	0.02		201		
	non noble metal	copper	7440-50-8	1428.770	66.89	66.98	668883	669754	
wire	non noble metal	aluminium	7429-90-5	3.035	0.14	0.14	1421	1421	
encapsulation	organic material	carbon black	1333-86-4	3.325	0.16		1557		
	plastics	epoxy resin	-	129.692	6.07		60716		
	inorganic material	silicondioxide	60676-86-0	532.069	24.91	31.14	249090	311363	
leadfinish	non noble metal	tin	7440-31-5	21.731	1.02	1.02	10173	10173	
plating	non noble metal	nickel	7440-02-0	1.786	0.08	0.08	836	836	
solder	non noble metal	antimony	7440-36-0	0.442	0.02		207		
	noble metal	silver	7440-22-4	1.104	0.05		517		
	non noble metal	tin	7440-31-5	2.870	0.13	0.20	1344	2068	
*deviation	< 10%					Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2011/65/EU (RoHS) and does not use any exemption.

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